

(12) United States Patent Huang

(10) Patent No.:

US 9,408,588 B2

(45) **Date of Patent:**

Aug. 9, 2016

(54) CMUT PACKAGING FOR ULTRASOUND **SYSTEM**

(75) Inventor: Yongli Huang, San Jose, CA (US)

Assignee: KOLO TECHNOLOGIES, INC., San

Jose, CA (US)

Subject to any disclaimer, the term of this (*) Notice:

patent is extended or adjusted under 35

U.S.C. 154(b) by 1150 days.

12/745,754 (21) Appl. No.:

(22) PCT Filed: Dec. 3, 2008

(86) PCT No.: PCT/US2008/085447

§ 371 (c)(1),

(2), (4) Date: Jun. 2, 2010

(87) PCT Pub. No.: WO2009/073753

PCT Pub. Date: Jun. 11, 2009

(65)**Prior Publication Data**

> US 2010/0280388 A1 Nov. 4, 2010

Related U.S. Application Data

(60) Provisional application No. 60/992,020, filed on Dec. 3, 2007, provisional application No. 61/024,843, filed on Jan. 30, 2008.

(51) Int. Cl. H01L 41/00 (2013.01)A61B 8/12 (2006.01)

(Continued)

(52) U.S. Cl.

CPC A61B 8/12 (2013.01); A61B 8/4483 (2013.01); **B06B 1/0292** (2013.01); A61B 8/445 (2013.01);

(Continued)

(58) Field of Classification Search

CPC B06B 1/065; B06B 11/00; B06B 3/00; A61B 8/12; H04R 31/00 USPC 600/459, 439, 457, 462, 466; 310/334; 438/48; 73/861.27; 367/181; 257/296,

See application file for complete search history.

(56)**References Cited**

U.S. PATENT DOCUMENTS

4,413,520 A 11/1983 Murakami et al. 4,603,589 A 8/1986 Machida (Continued)

FOREIGN PATENT DOCUMENTS

ΙP 10192281 7/1998 JP 11501245 2/1999 (Continued)

OTHER PUBLICATIONS

Translated Chinese Office Action mailed Nov. 30, 2011 for Chinese patent application No. 200880117507.8, a counterpart foreign application of U.S. Appl. No. 12/745,758, 18 pages.

(Continued)

Primary Examiner — Vani Gupta (74) Attorney, Agent, or Firm — Mattingly & Malur, PC

ABSTRACT

Ultrasonic scanners and methods of manufacturing ultrasonic scanners. One embodiment of a method includes integrating a flexible electronic device (e.g. an IC) and a flexible ultrasonic transducer (e.g. a portion of a circular CMUT array) with a flexible member. The IC, the transducer, and the flexible member can form a flexible subassembly which is rolled up to form an ultrasonic scanner. The integration of the IC and the transducer can occur at the same time. In the alternative, the integration of the electronic device can occur before the integration of the transducer. Moreover, the integration of the transducer can include using a semiconductor technique. Furthermore, the rolled up subassembly can form a lumen or can be attached to a lumen. The method can include folding a portion of the flexible subassembly to form a forward looking transducer. The flexible member of some subassemblies can include a pair of arms.

33 Claims, 12 Drawing Sheets

